MOSFET – Power, N-Channel, SUPERFET III, FRFET

650 V, 20 A, 190 m Ω

NTP190N65S3HF

Description

SUPERFET III MOSFET is ON Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advanced technology is tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate.

Consequently, SUPERFET III MOSFET is very suitable for the various power system for miniaturization and higher efficiency.

SUPERFET III FRFET MOSFET's optimized reverse recovery performance of body diode can remove additional component and improve system reliability.

Features

- 700 V @ $T_J = 150^{\circ}C$
- Typ. R_{DS(on)} = 159 mΩ
- Ultra Low Gate Charge (Typ. Q_g = 34 nC)
- Low Effective Output Capacitance (Typ. Coss(eff.) = 316 pF)
- 100% Avalanche Tested
- These Devices are Pb-Free and are RoHS Compliant

Applications

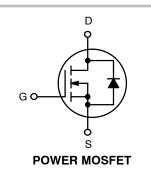
- Computing / Display Power Supplies
- Telecom / Server Power Supplies
- Industrial Power Supplies
- Lighting / Charger / Adapter

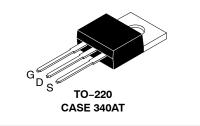


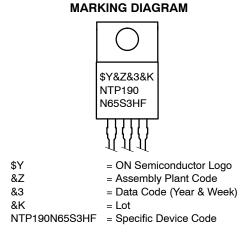
ON Semiconductor®

www.onsemi.com

V _{DSS}	R _{DS(ON)} MAX	I _D MAX
650 V	190 m Ω @ 10 V	20 A







ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

Symbol	Parameter	Value	Unit	
V _{DSS}	Drain to Source Voltage	o Source Voltage		
V _{GSS}	Gate to Source Voltage	– DC	±30	V
		– AC (f > 1 Hz)	±30	
I _D	Drain Current	– Continuous (T _C = 25°C)	20	А
		– Continuous (T _C = 100°C)	12.7	
I _{DM}	Drain Current	rrent - Pulsed (Note 1)		А
E _{AS}	Single Pulsed Avalanche Energy (Note 2)		220	mJ
I _{AS}	Avalanche Current (Note 2)		3.7	А
E _{AR}	Repetitive Avalanche Energy (Note 1)		1.62	mJ
dv/dt	MOSFET dv/dt		100	V/ns
	Peak Diode Recovery dv/dt (Note 3)		50	
PD	Power Dissipation	(T _C = 25°C)	162	W
		– Derate Above 25°C	1.3	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C
ΤL	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 seconds		300	°C

ABSOLUTE MAXIMUM RATINGS (T_C = 25°C, Unless otherwise noted)

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality shows be assumed, damage may occur and reliability may be affected. 1. Repetitive rating: pulse-width limited by maximum junction temperature. 2. $I_{AS} = 3.7 \text{ A}, R_G = 25 \Omega$, starting $T_J = 25^{\circ}C$. 3. $I_{SD} \le 10 \text{ A}, \text{ di/dt} \le 200 \text{ A/}\mu\text{s}, V_{DD} \le 400 \text{ V}, \text{ starting } T_J = 25^{\circ}C$.

THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.77	°C/W
R _{θJA}	Thermal Resistance, Junction to Ambient, Max.	62.5	

PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Marking	Package	Packing Method	Reel Size	Tape Width	Quantity
NTP190N65S3HF	NTP190N65S3HF	TO-220	Tube	N/A	N/A	50 Units

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

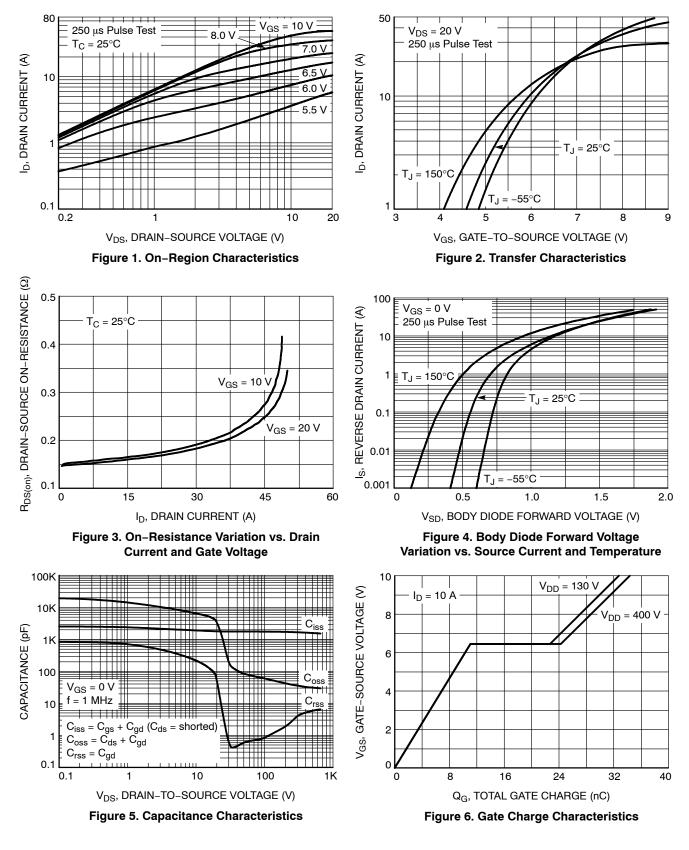
Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
OFF CHARACT	ERISTICS			•		
BV _{DSS}	Drain to Source Breakdown Voltage	$V_{GS} = 0 V, I_D = 1 mA, T_J = 25^{\circ}C$ 65				V
		V_{GS} = 0 V, I_{D} = 1 mA, T_{J} = 150 $^{\circ}C$	700			V
$\Delta \text{BV}_{\text{DSS}}\!/\!\Delta\text{T}_{\text{J}}$	Breakdown Voltage Temperature Coefficient	$I_D = 10$ mA, Referenced to 25°C		0.65		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 650 V, V_{GS} = 0 V			10	μA
		V_{DS} = 520 V, T_C = 125 °C		65		
I _{GSS}	Gate to Body Leakage Current	V_{GS} = ± 30 V, V_{DS} = 0 V			±100	nA
ON CHARACTE	RISTICS					
V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = 0.43$ mA	3.0		5.0	V
R _{DS(on)}	Static Drain to Source On Resistance	V_{GS} = 10 V, I _D = 10 A		159	190	mΩ
9 _{FS}	Forward Transconductance	V_{DS} = 20 V, I_{D} = 10 A		11		S
OYNAMIC CHA	RACTERISTICS				•	•
C _{iss}	Input Capacitance			1610		pF
C _{oss}	Output Capacitance	V_{DS} = 400 V, V_{GS} = 0 V, f = 1 MHz		30		pF
C _{oss(eff.)}	Effective Output Capacitance	V_{DS} = 0 V to 400 V, V_{GS} = 0 V		316		pF
C _{oss(er.)}	Energy Related Output Capacitance	V_{DS} = 0 V to 400 V, V_{GS} = 0 V		59		pF
Q _{g(tot)}	Total Gate Charge at 10 V			34		nC
Q _{gs}	Gate to Source Gate Charge	V _{DS} = 400 V, I _D = 10 A, V _{GS} = 10 V (Note 4)		11		nC
Q _{gd}	Gate to Drain "Miller" Charge	(13		nC
ESR	Equivalent Series Resistance	f = 1 MHz		6.8		Ω
WITCHING CH	IARACTERISTICS					
t _{d(on)}	Turn-On Delay Time			19		ns
t _r	Turn-On Rise Time	$V_{DD} = 400 \text{ V}, I_D = 10 \text{ A},$		19		ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, \text{ R}_{g} = 4.7 \Omega$ (Note 4)		58		ns
t _f	Turn-Off Fall Time			14		ns

SOURCE-DRAIN DIODE CHARACTERISTICS

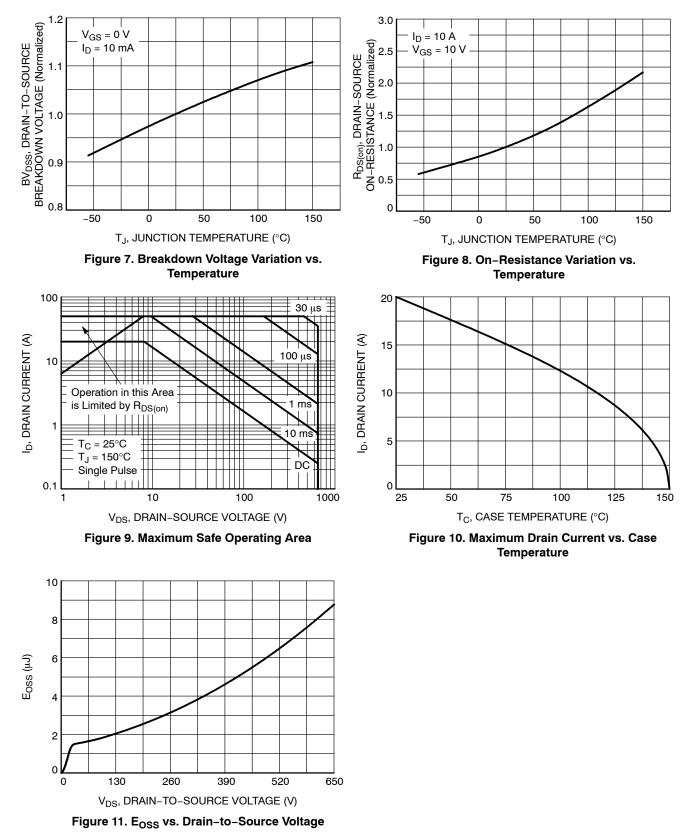
۱ _S	Maximum Continuous Source to Drain Diode Forward Current				20	А
I _{SM}	Maximum Pulsed Source to Drain Diode Forward Current				50	Α
V _{SD}	Source to Drain Diode Forward Voltage	V_{GS} = 0 V, I _{SD} = 10 A			1.3	V
t _{rr}	Reverse Recovery Time	V _{DD} = 400 V, I _{SD} = 10 A,		80		ns
Q _{rr}	Reverse Recovery Charge	dl _F /dt = 100 A/μs		264		nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 4. Essentially independent of operating temperature typical characteristics.

TYPICAL CHARACTERISTICS



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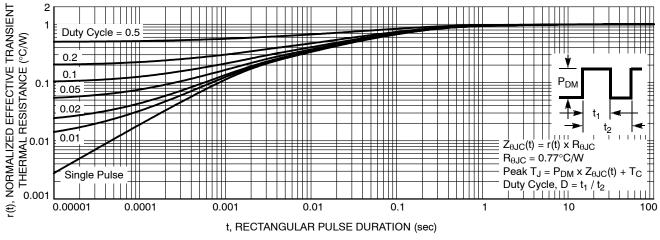
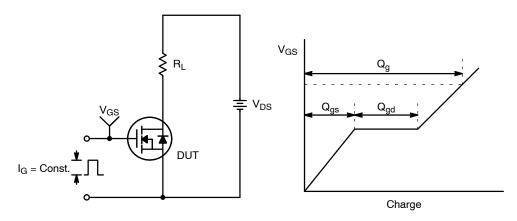


Figure 12. Transient Thermal Response Curve





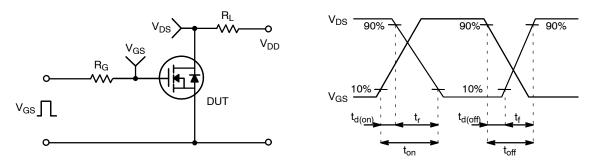
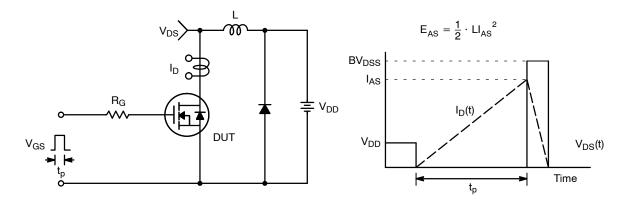


Figure 14. Resistive Switching Test Circuit & Waveforms





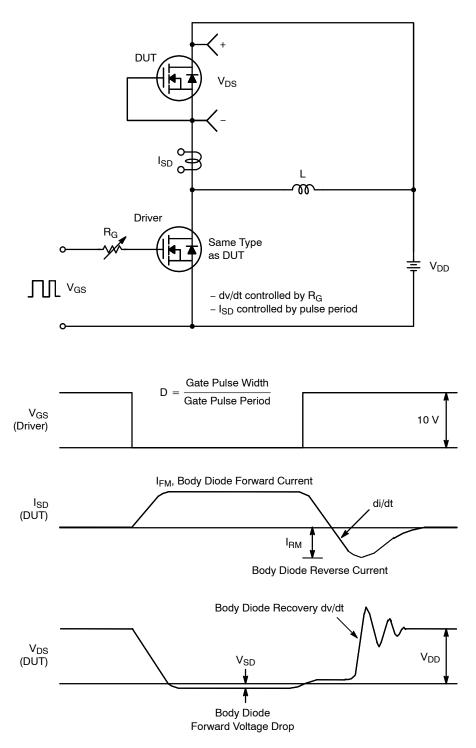
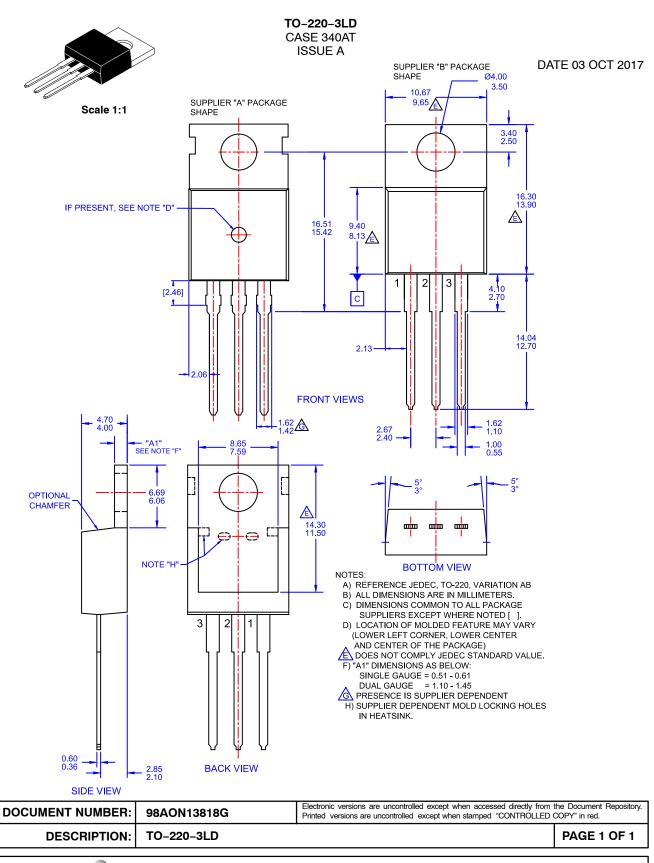


Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms

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